



General Description

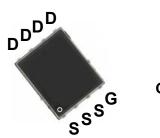
These N-Channel enhancement mode power field effect transistors are using SGT MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

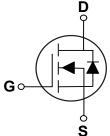
BV _{DSS}	R _{DS(ON)}	I _D
40 V	1 mΩ	200 A

Features

- $\cdot R_{DS(ON)} \le 1 m\Omega @V_{GS} = 10V$
- Fast Switching
- · Improved dv/dt Capability
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- · BMS
- BLDC
- UPS

Absolute Maximum Ratings T _C =25°C unless otherwise noted							
Symbol	Parameter	Rating	Units				
V_{DS}	Drain-Source Voltage	40	V				
V_{GS}	Gate-Source Voltage	±20	V				
I _D	Drain Current - Continuous (T _C =25°C)	200	Α				
I _{DM}	Drain Current - Pulsed (NOTE 1)	800	Α				
P _D	Power Dissipation (T _C =25°C)	68	W				
T_J	Operating Junction Temperature Range	-55 to 150	°C				
T _{STG}	Storage Temperature Range	-55 to 150	°C				
Marking Code		ND1P0					

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	62	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	1.4	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	40			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =40V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			1.0	- mΩ
		V _{GS} =4.5V , I _D =15A			1.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0		2.5	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			125		
Q_{gs}	Gate-Source Charge	V_{DS} =20V , V_{GS} =10V , I_{D} =85A		18		nC
Q_{gd}	Gate-Drain Charge	1		13		
$T_{d(on)}$	Turn-On Delay Time			14.1		
T _r	Rise Time	V_{DD} =20V , V_{GS} =10V , R_{G} =1.6 Ω , I_{D} =85A		7.9		nS
$T_{d(off)}$	Turn-Off Delay Time			56.5		113
T_f	Fall Time			9.6		
C _{iss}	Input Capacitance			7400		
C_{oss}	Output Capacitance	V_{DS} =20V , V_{GS} =0V , F=1MHz		1930		pF
C_{rss}	Reverse Transfer Capacitance			110		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			200	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =20A			1.2	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





Characteristics Curves

FIG. 1-Drain Current

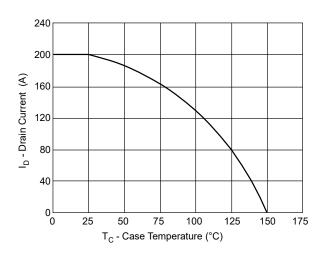


FIG. 2-Normalized BV_{DSS} vs T_J

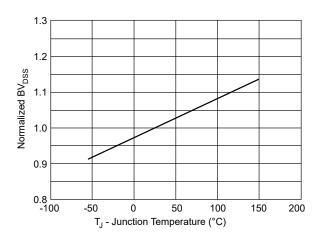


FIG. 2-Normalized $R_{\text{DS}(\text{ON})}\,\text{vs}\;T_{\text{J}}$

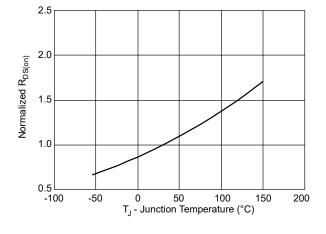


FIG. 4-Gate Charge Characteristics

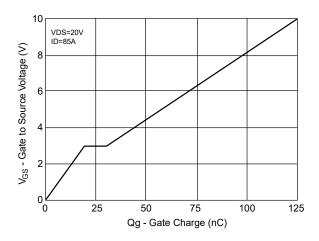


FIG. 5-Safe Operation Area

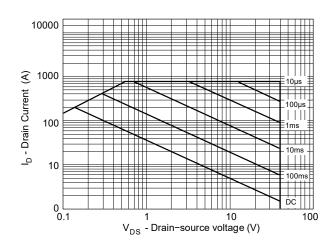
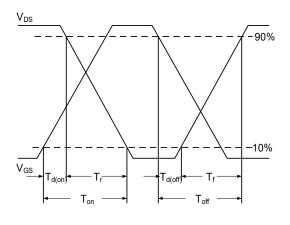


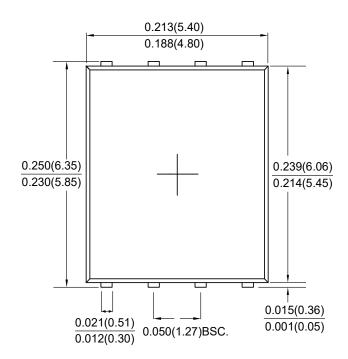
FIG. 6 - Switching Time Waveform

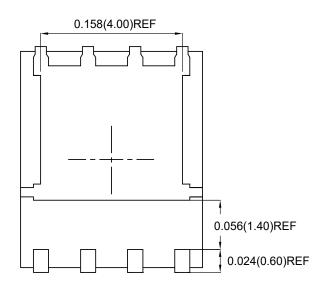


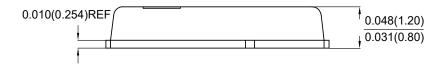


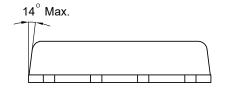


Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





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